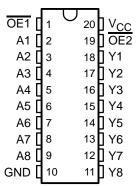
SN54HCT540, SN74HCT540 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

SCLS008C - MARCH 1984 - REVISED MARCH 2003

- Operating Voltage Range of 4.5 V to 5.5 V
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 12 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Inputs Are TTL-Voltage Compatible
- High-Current 3-State Outputs Interface Directly With System Bus or Can Drive Up To 15 LSTTL Loads
- Data Flow-Through Pinout (All Inputs on Opposite Side From Outputs)

SN54HCT540 . . . J PACKAGE SN74HCT540 . . . DW OR N PACKAGE (TOP VIEW)



description/ordering information

These octal buffers and line drivers are designed to have the performance of the 'HCT240 devices and a pinout with inputs and outputs on opposite sides of the package. This arrangement greatly facilitates printed circuit board layout.

The 3-state control gate is a 2-input NOR. If either output-enable ($\overline{OE1}$ or $\overline{OE2}$) input is high, all eight outputs are in the high-impedance state. The 'HCT540 devices provide inverted data at the outputs.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

TA	T _A PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N Tube		SN74HCT540N	SN74HCT540N
-40°C to 85°C	SOIC - DW	Tube	SN74HCT540DW	HCT540
	SOIC - DW	Tape and reel	SN74HCT540DWR	HC1540
–55°C to 125°C	CDIP – J	Tube	SNJ54HCT540J	SNJ54HCT540J

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each buffer/driver)

	INPUTS	OUTPUT	
OE1	OE2	Y	
L	L	L	Н
L	L	Н	L
Н	X	Χ	Z
Χ	Н	Χ	Z



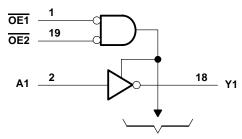
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SN54HCT540, SN74HCT540 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

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logic diagram (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	$\dots \dots \pm 20 \text{ mA}$
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	±20 mA
Continuous output current, I _O (V _O = 0 to V _{CC})	±35 mA
Continuous current through V _{CC} or GND	±70 mA
Package thermal impedance, θ _{JA} (see Note 2): DW package	58°C/W
N package	69°C/W
Storage temperature range, T _{stg}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN	54HCT5	40	SN	74HCT5	40	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	ONIT
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	2			2			V
VIL	Low-level input voltage	V _{CC} = 4.5 V to 5.5 V			8.0			0.8	V
VI	Input voltage		0		VCC	0		VCC	V
VO	Output voltage		0		VCC	0		VCC	V
t _t	Input transition (rise and fall) time				500			500	ns
T _A	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CO	NDITIONS	V	Т	A = 25°C	;	SN54H	CT540	SN74H	CT540	UNIT
PARAMETER	lesi co	NDITIONS	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
Vari	\\. = \\ or \\	$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4		V
VOH	$V_I = V_{IH}$ or V_{IL}	$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84]
Vol	VI = VIH or VIL	I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1	V
VOL	AI = AIH OL AIL	$I_{OL} = 6 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	V
lį	VI = VCC or 0		5.5 V		±0.1	±100		±1000		±1000	nA
loz	$V_O = V_{CC}$ or 0,	$V_I = V_{IH}$ or V_{IL}	5.5 V		±0.01	±0.5		±10		±5	μΑ
Icc	$V_I = V_{CC}$ or 0,	I _O = 0	5.5 V			8		160		80	μΑ
ΔI _{CC} †	One input at 0.5 V or 2.4 V, Other inputs at 0 or V _{CC}		5.5 V		1.4	2.4		3		2.9	mA
Ci			4.5 V to 5.5 V		3	10		10		10	pF

This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or VCC.

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	Vaa	T _A = 25°C			SN54HCT540		SN74HCT540		UNIT	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
	А	Y	4.5 V		13	20		30		25	ne	
^t pd	A	•	5.5 V		12	18		27		23	ns	
	<u> </u>	Y	4.5 V		20	30		45		38	20	
t _{en}	ŌĒ	'	5.5 V		18	27		41		34	ns	
.	ŌĒ	V	4.5 V		19	30		45		38	20	
^t dis	OE	ī	5.5 V		18	27		41		34	ns	
+.		٧	4.5 V		8	12		18		15	ne	
t _t		•	5.5 V		7	11		16		14	ns	

switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 1)

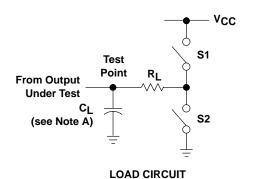
PARAMETER	FROM	TO (OUTPUT)	V	T _A = 25°C			SN54HCT540		SN74HCT540		UNIT
PARAMETER	(INPUT)		Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
. .	Α	V	4.5 V		20	30		45		38	20
^t pd	A	ī	5.5 V		19	27		41		34	ns
		V	4.5 V		26	40		60		50	
^t en	ŌĒ	ī	5.5 V		25	36		54		45	ns
		V	4.5 V		17	42		63		53	no
Чt		Y .	5.5 V		14	38		57		48	ns

operating characteristics, $T_A = 25^{\circ}C$

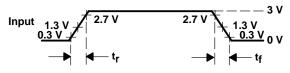
	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per buffer/driver	No load	35	pF



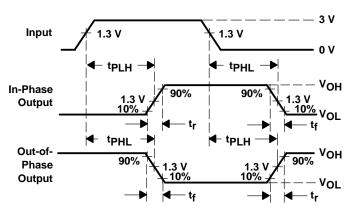
PARAMETER MEASUREMENT INFORMATION

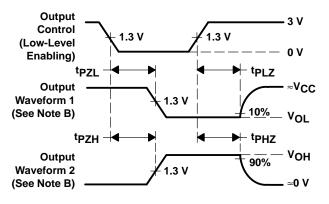


PARA	METER	RL	CL	S1	S2
•	tPZH	1 k Ω	50 pF	Open	Closed
чen			150 pF	Closed	Open
	tPHZ	1 k Ω	50 pF	Open	Closed
^t dis	tPLZ	1 K22	30 pi	Closed	Open
t _{pd} or	t _t	_	50 pF or 150 pF	Open	Open



VOLTAGE WAVEFORM INPUT RISE AND FALL TIMES





VOLTAGE WAVEFORMS PROPAGATION DELAY AND OUTPUT RISE AND FALL TIMES

VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f = 6 \text{ ns}$, $t_f = 6 \text{ ns}$.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpz and tpzH are the same as ten.
- G. tplH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
						(4)	(5)		
JM38510/65760BRA	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 65760BRA
JM38510/65760BRA.A	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 65760BRA
M38510/65760BRA	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 65760BRA
SN54HCT540J	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54HCT540J
SN54HCT540J.A	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54HCT540J
SN74HCT540DWR	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT540
SN74HCT540DWR.A	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT540
SN74HCT540DWRG4	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT540
SN74HCT540N	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HCT540N
SN74HCT540N.A	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HCT540N
SNJ54HCT540J	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54HCT540J
SNJ54HCT540J.A	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54HCT540J

⁽¹⁾ Status: For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE OPTION ADDENDUM

www.ti.com 7-Oct-2025

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54HCT540, SN74HCT540:

Catalog: SN74HCT540

Military: SN54HCT540

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HCT540DWR	SOIC	DW	20	2000	330.0	24.4	10.9	13.3	2.7	12.0	24.0	Q1
SN74HCT540DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

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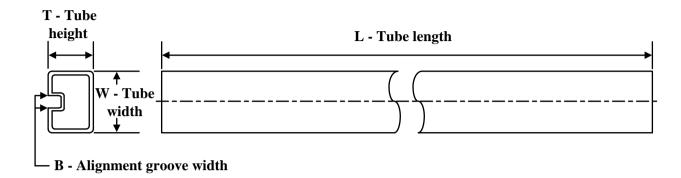
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HCT540DWR	SOIC	DW	20	2000	356.0	356.0	45.0
SN74HCT540DWR	SOIC	DW	20	2000	356.0	356.0	45.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74HCT540N	N	PDIP	20	20	506	13.97	11230	4.32
SN74HCT540N.A	N	PDIP	20	20	506	13.97	11230	4.32

14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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